

Patent Abstracts of Japan

PUBLICATION NUMBER : 11116942
PUBLICATION DATE : 27-04-99

APPLICATION DATE : 14-10-97
APPLICATION NUMBER : 09280592

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INT.CL. : C09K 3/14 H01L 21/304

TITLE : ABRASIVE COMPOSITION

ABSTRACT : PROBLEM TO BE SOLVED: To obtain an abrasive composition for silicon semiconductor wafers capable of reducing particles adhering to wafer surfaces without lowering the haze level and the surface roughness-improving properties in the mirror polishing of silicon semiconductor wafers.

SOLUTION: An abrasive composition for silicon semiconductor wafers comprises (a) silicon dioxide, (b) water, (c) a water soluble polymeric compound, (d) a basic compound and (e) 0.001-30 wt.%, based on the abrasive composition, of a compound having 1-10 alcoholic hydroxyl groups, or components (a), (b) and (c) and (d') 0.001-30 wt.%, based on the abrasive composition, of a nitrogen- containing basic compound having 1-10 alcoholic hydroxyl groups.

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